Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A method of assembling an integrated circuit (IC) device with a substrate, ~~assembly, the method~~ comprising:

providing a substrate having electrical terminals on a first side of the substrate, and a copper bondpad on a second side of the substrate opposing the first side~~; the bondpad~~ electrically coupled to at least one of the terminals;

the copper bondpad being substantially free of plated gold and substantially free of solder material;

mounting ~~an integrated circuit~~ the IC chip to the first side of the substrate ~~, the integrated circuit component having a lead adapted to be wire-bonded to the terminal~~;

electrically connecting the IC chip to the terminals;

encapsulating the IC chip mounted on the substrate with encapsulation material at an elevated temperature, whereby oxidizing the surface of the copper bondpad; ~~and~~

~~removing~~ spraying an aqueous etchant on the bondpad to remove oxidized copper ~~oxidation~~ from the bondpad~~, the bondpad adapted to be metallurgically bonded to a trace on a printed circuit board.~~; and

coating the etched bondpad with an anti-tarnish solution.

2. (canceled)

3. (currently amended) [A] The method according to claim [2] 1, further comprising rinsing the etchant with deionized water ~~prior to coating the bondpad~~.

4. (currently amended) [A] The method according to claim [2] 1, wherein ~~the bondpad comprises copper and~~ the etchant comprises potassium peroxymonosulfate.

5. (currently amended) [A] The method according to claim 4, wherein the etchant comprises from about 80 grams to about 120 grams of potassium peroxymonosulfate per liter of water.

6. (currently amended) [A] The method according to claim 5, wherein the etchant further comprises from about 1% to about 3% sulfuric acid ~~per~~ by volume.

7. (currently amended) [A] The method according to claim 6, wherein ~~removing oxidation further comprises removing oxidation~~ the spraying an aqueous etchant is performed at about room temperature.

8. (canceled)

9. (currently amended) [A] The method according to claim 1, ~~8, wherein metallurgically bonding~~ further ~~comprises~~ comprising removing the anti-tarnish coating from the bondpad ~~with flux~~.

10. (currently amended) [A] The method according to claim [8] 1, wherein the anti-tarnish solution comprises methyl alcohol, benzotriazole, a nonionic surfactant, and water.

11. (currently amended) [A] The method according to claim 10, wherein the anti-tarnish solution comprises about 5% methyl alcohol, about 1% benzotriazole, about 3% nonionic surfactant, and about 91% water.

12. (currently amended) [A] The method according to claim 11, wherein the anti-tarnish solution further comprises from about 1% to about 2.5% sulfuric acid [per] by volume.

13. (currently amended) [A] The method according to claim 12, wherein the coating ~~the bondpad further comprises coating the bondpad with an anti-tarnish solution in~~ is performed at a temperature of about 60°C.

14. (currently amended) [A] The method according to claim 1, ~~wherein metallurgically bonding comprises~~ further comprising metallurgically bonding the bondpad to ~~the trace~~ a PCB using a solder ball.

15 – 20. (canceled)

21. (new) A method of forming an integrated circuit (IC) device with an improved substrate, comprising:

providing a substrate having terminals on a first side and copper bondpads on a second side, the outer surface of the copper bondpads substantially free of plated gold, substantially free of plated nickel, and substantially free of solder material;

attaching an integrated circuit chip on the first side and electrically connecting the chip to the terminals;

encapsulating the circuit chip attached to the substrate with encapsulation material at an elevated temperature whereby oxidizing the surface of the copper bondpads;

submerging the substrate with the encapsulated IC chip in an aqueous etchant to remove oxidized copper from the bondpads; and

coating the etched bondpads with an anti-tarnish solution .

22. (new) The method of claim 21, further comprising mounting the IC device on a PCB.

23. (new) The method of claim 21, further comprising electrically connecting the bondpads to conductive traces on the PCB.

24. (new) The method of claim 23, in which the connecting further comprising applying solder material to the bondpads.

25. (new) The method of 24, further comprising removing the anti-tarnish coating prior to applying solder material to the bondpads.